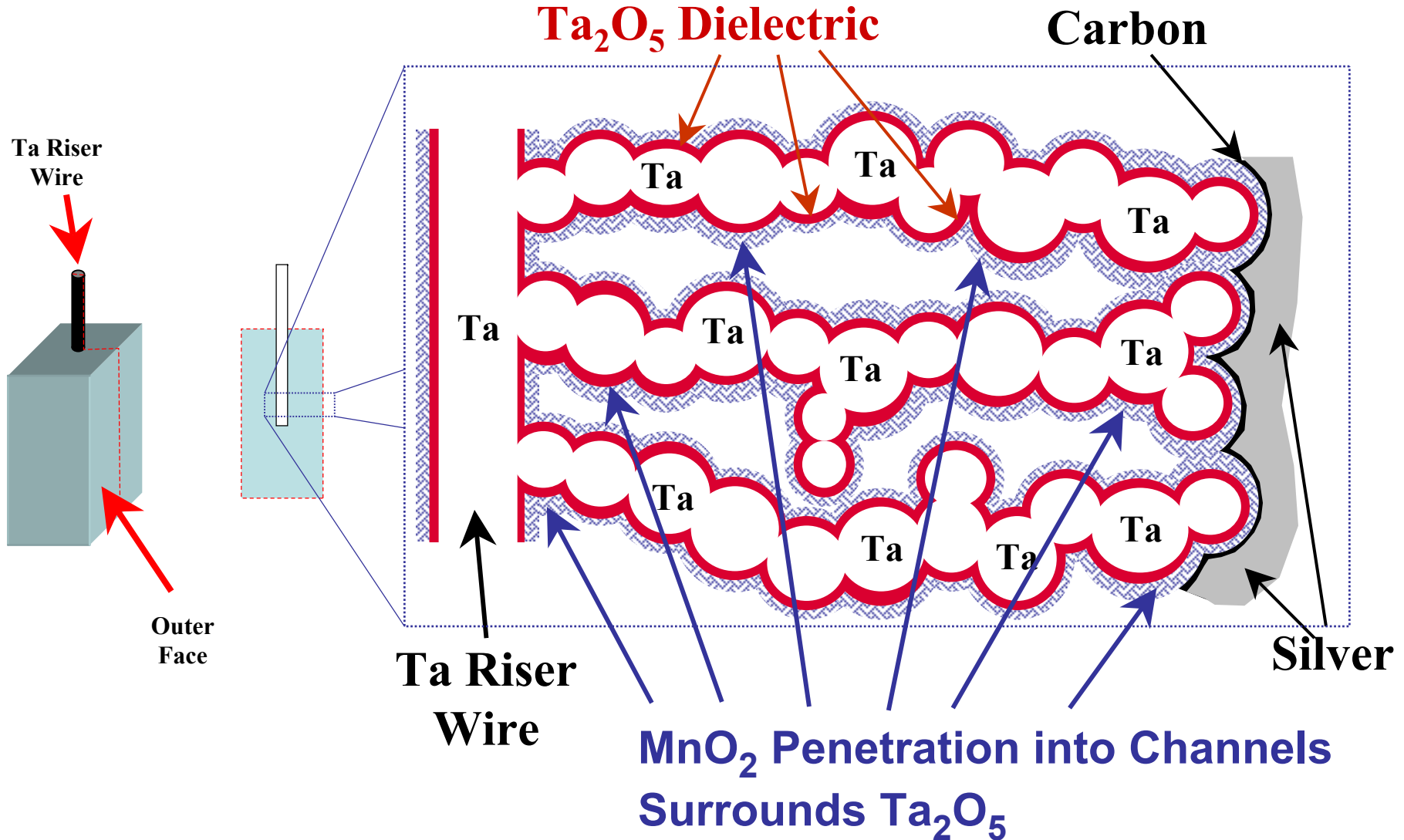
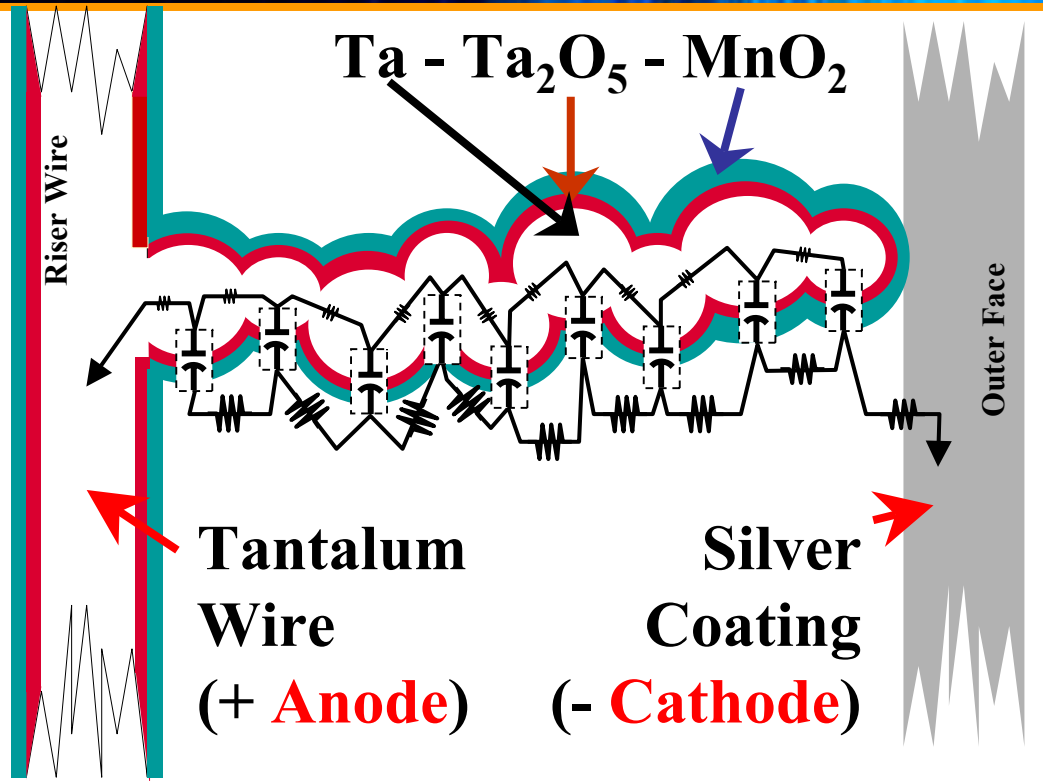


**Benefits of Conductive Polymer  
as Cathode System  
in Tantalum Capacitors  
“KO”  
(KEMET Organic)**

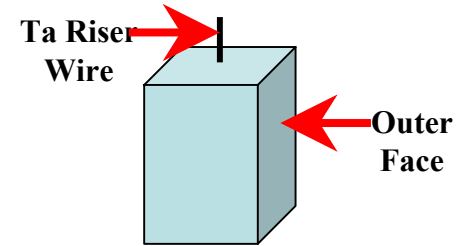
# Tantalum Construction



# Electrolytic RC-Ladder Structure



## RC-Ladder Effects



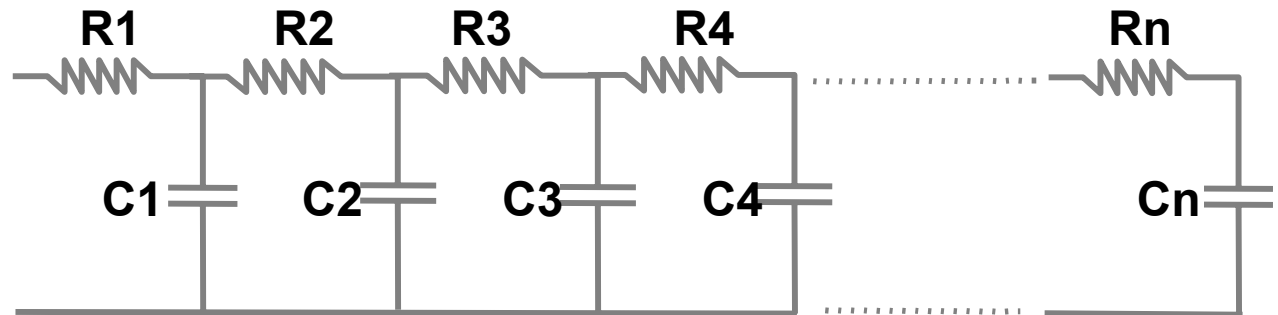
$$tc1 = C1 \times R1$$

$$tc2 = C2 \times (R1 + R2)$$

$$tc3 = C3 \times (R1 + R2 + R3)$$

$$tcn = Cn \times (R1 + R2 + R3 \dots + Rn)$$

RC-Ladder effects are factored by both capacitance and resistance.



# Electrolytic's Loss of Capacitance

T495X477M006AS

File Print Plot Temp Adj. Change Plot MonitorXY Bias Change Add RL About... Mult Plots Help

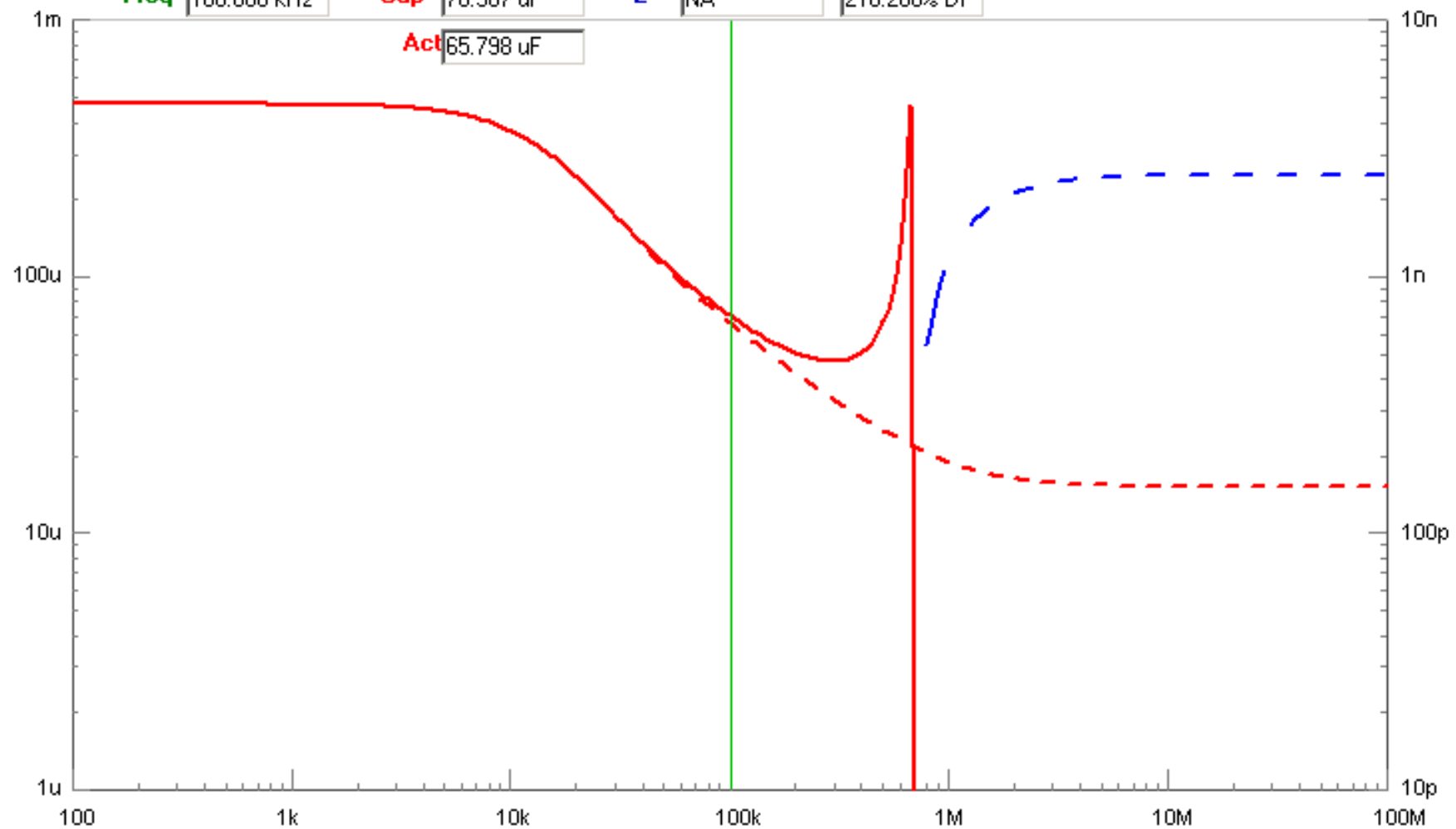
T495X477M006AS @ +25°C with 3.15VDC Bias

Measured Capacitance (F)

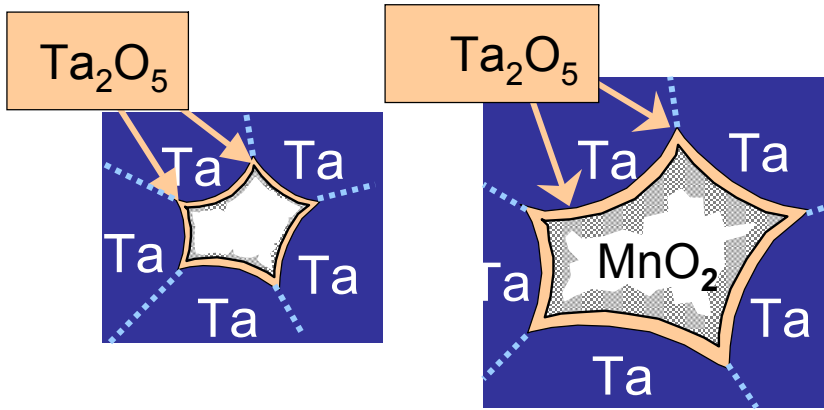
Measured Inductance (H)

Freq  Cap  L

Act

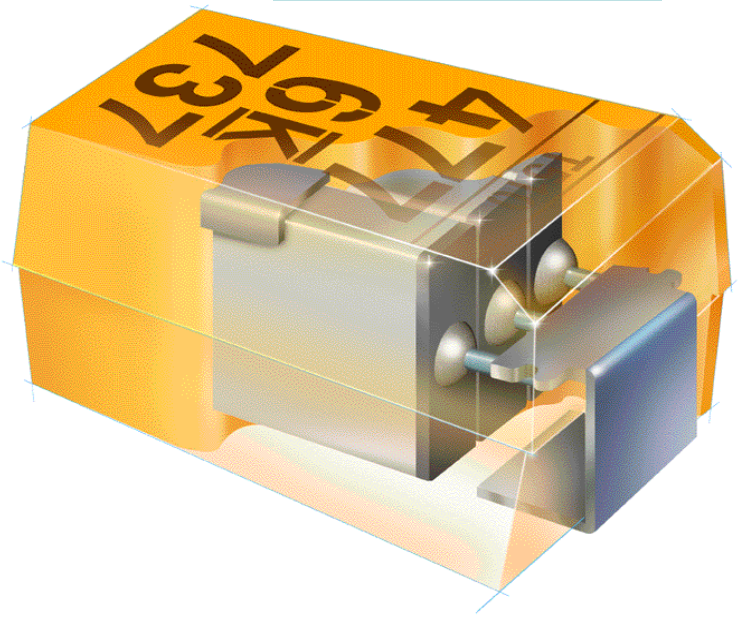


## Lower Capacitance Loss with Frequency



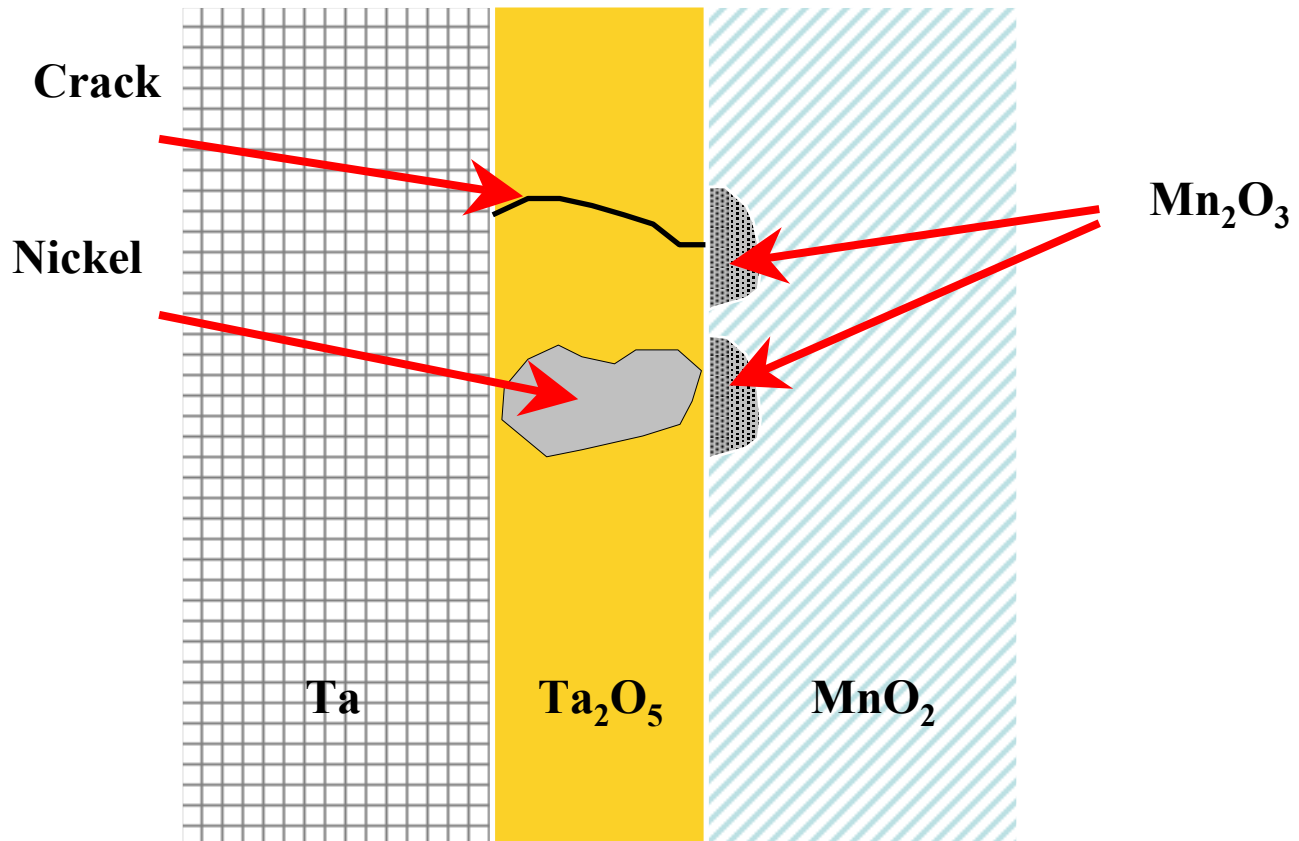
**T495**  
Larger Pores  
More MnO2  
Lower ESR

**T510**  
Multiple-pellets  
Lower ESR

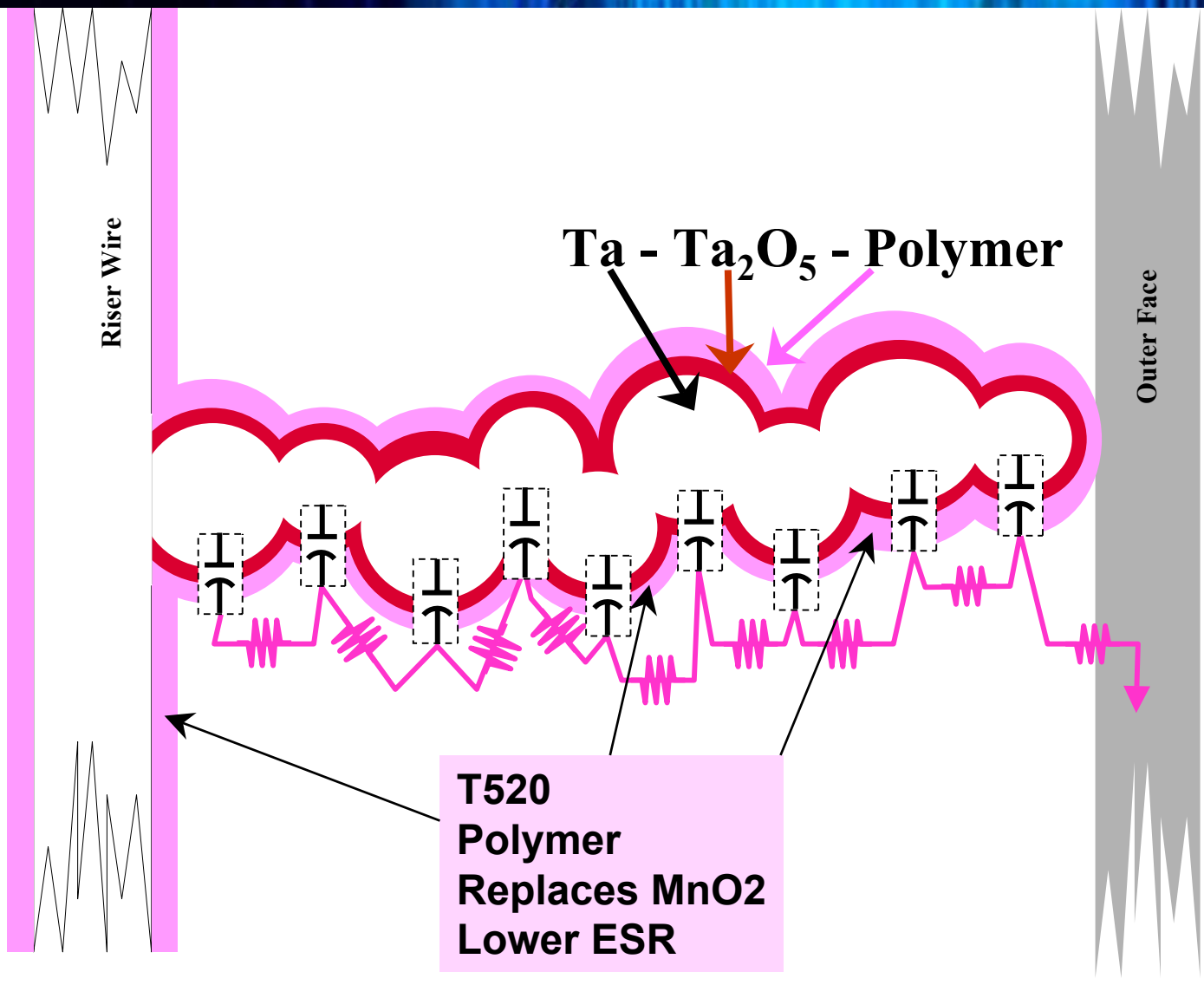


# MnO<sub>2</sub> Self-Healing

## Healing Effect of MnO<sub>2</sub> Layer

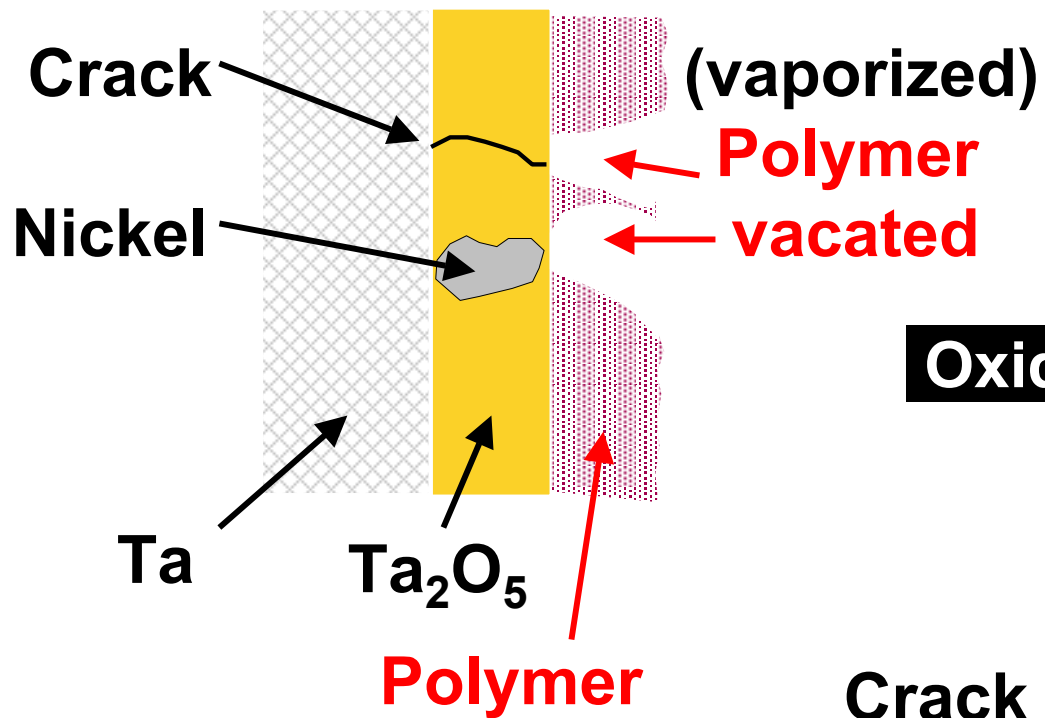


# Conductive Polymer replacing MnO<sub>2</sub>

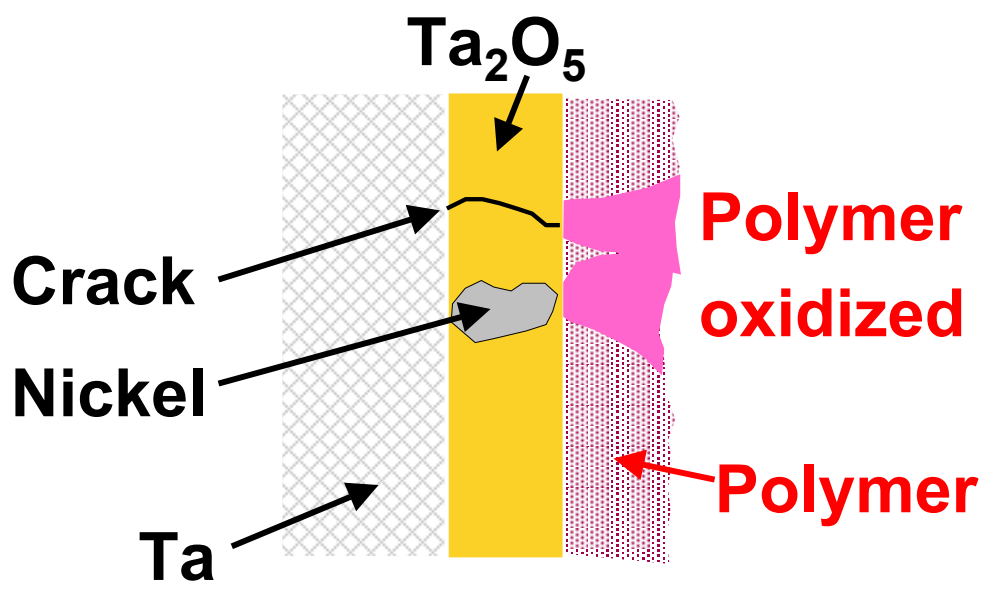


# Polymer Self-Healing

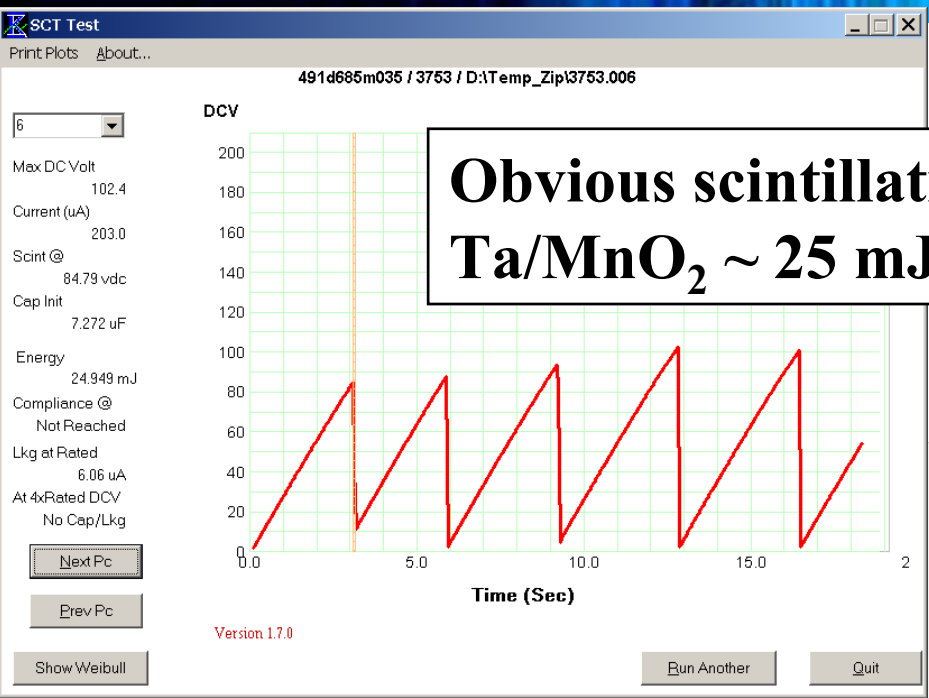
## Evaporation of Conductive Polymer Layer



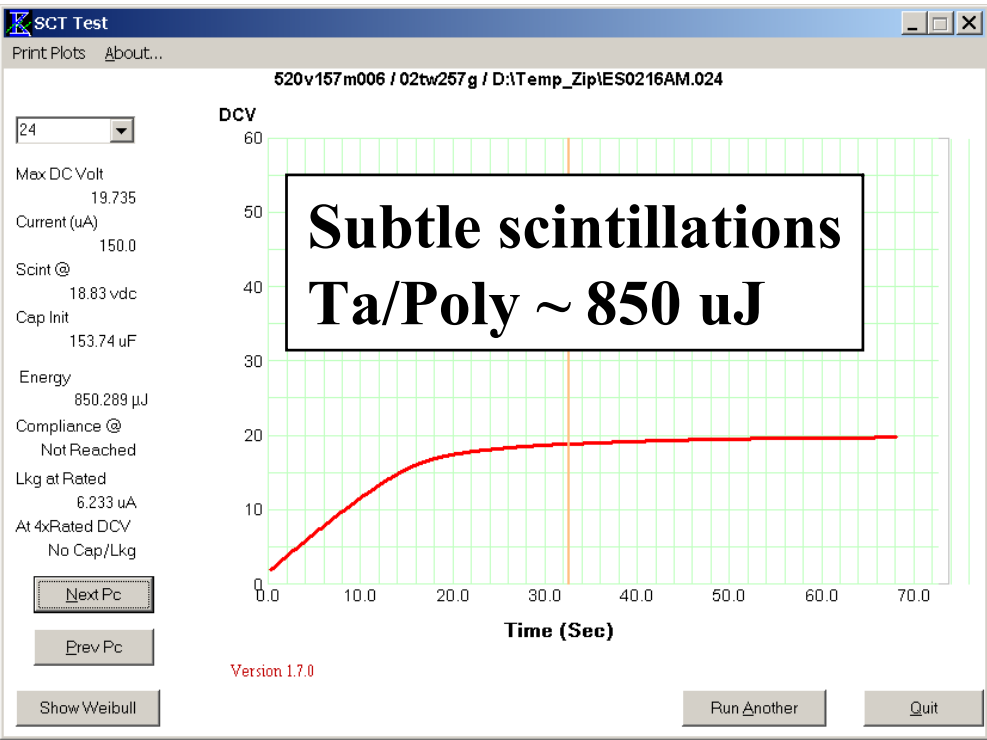
## Oxidation of Polymer Layer



# Scintillations (Captured Self-Healing)



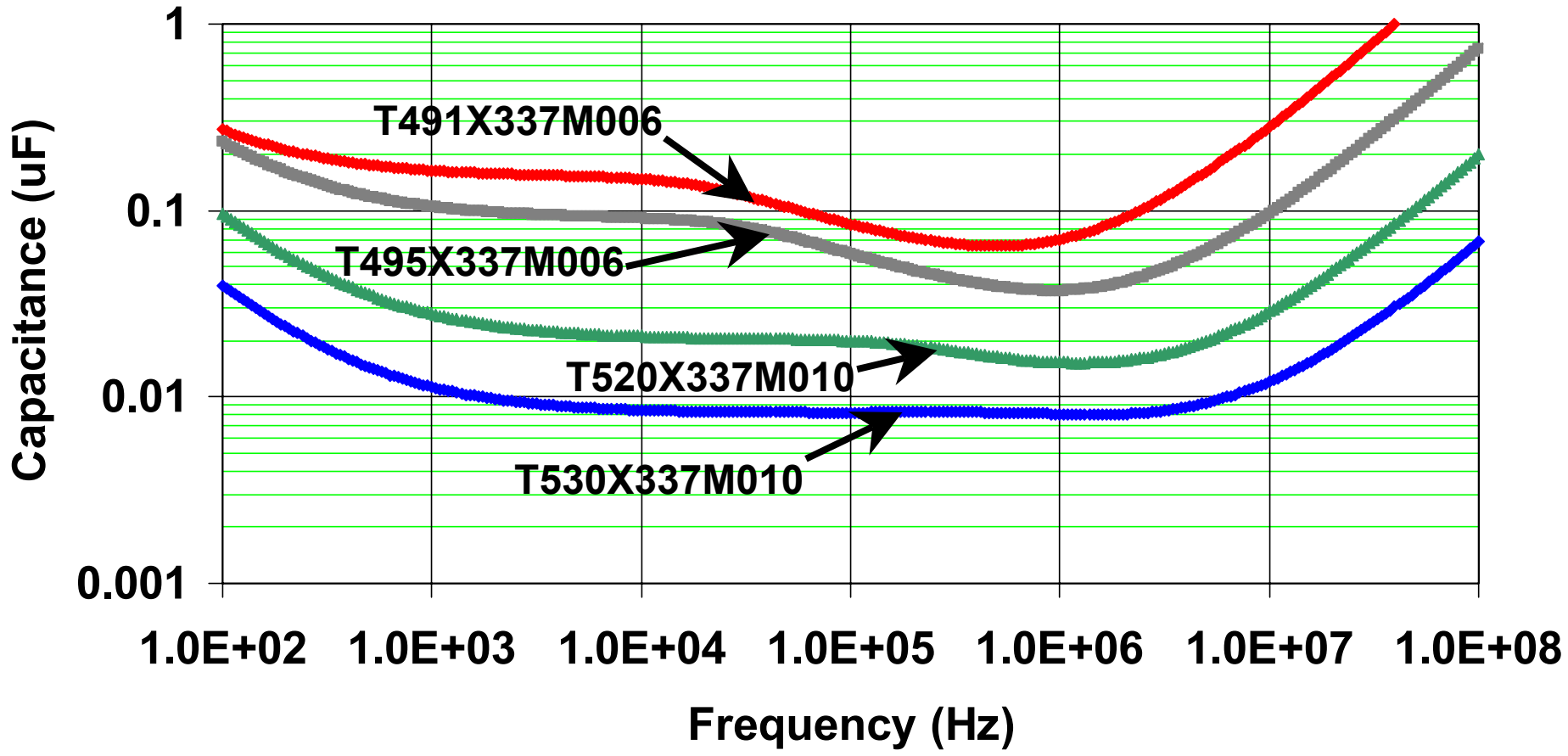
**Obvious scintillations  
 Ta/MnO<sub>2</sub> ~ 25 mJ**



**Subtle scintillations  
 Ta/Poly ~ 850 uJ**

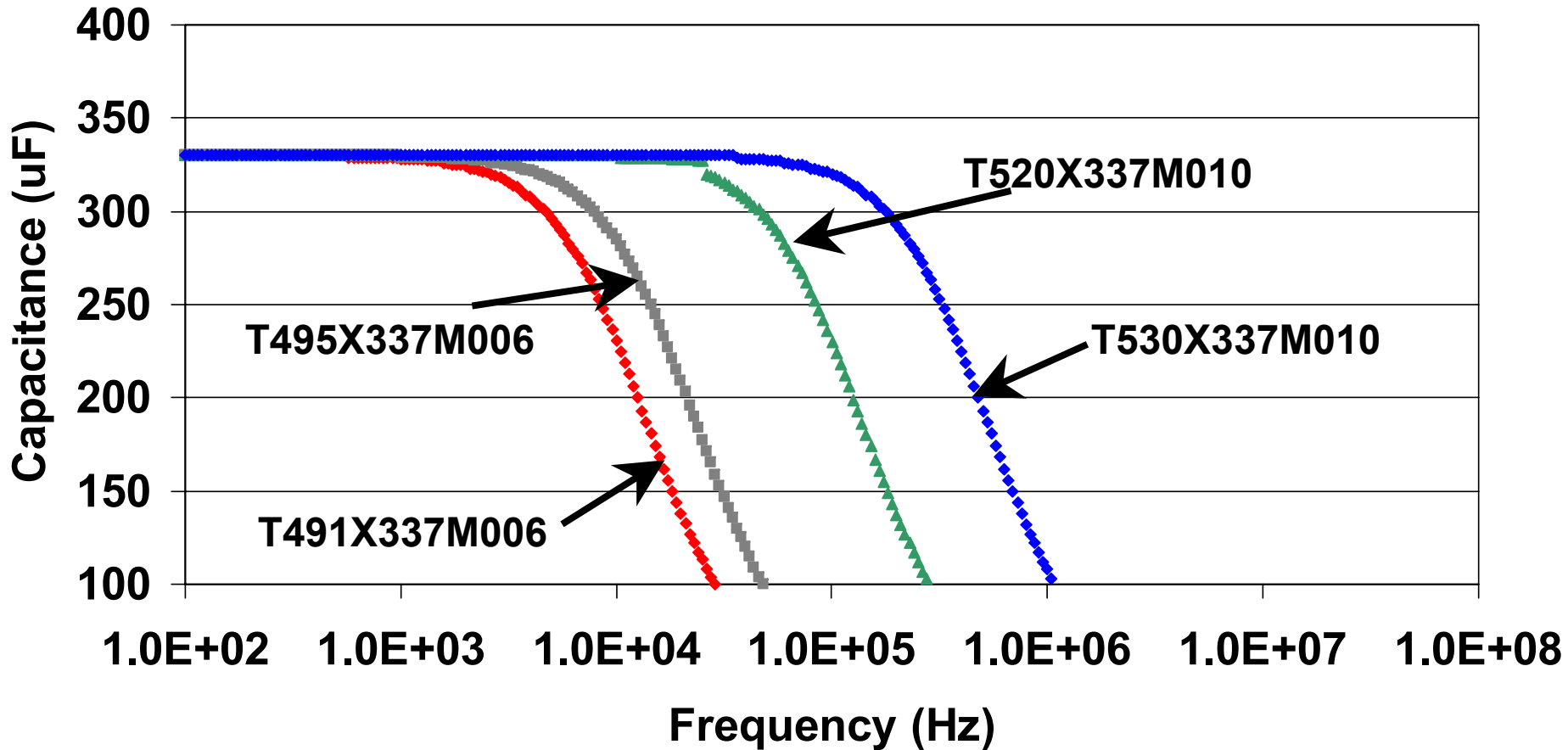
# Improvements in Tantalum - ESR

## 330 uF SMT Tantalum Chips



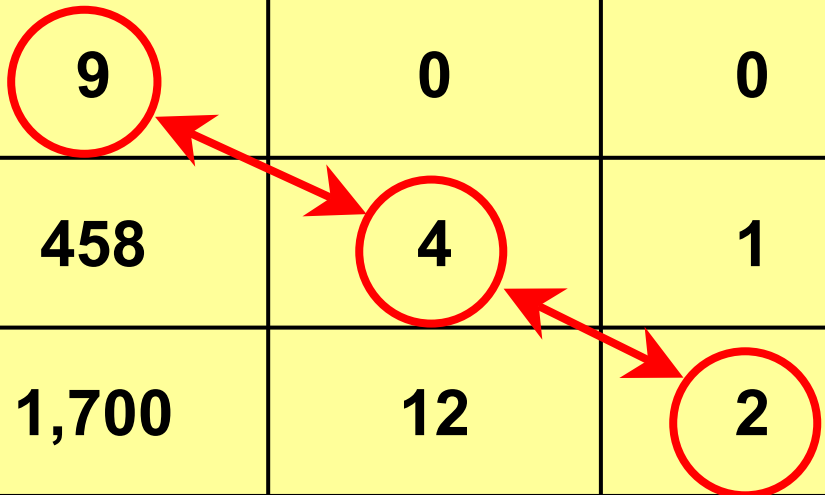
# Improvements in Tantalum

## 330 $\mu$ F SMT Tantalum Chips

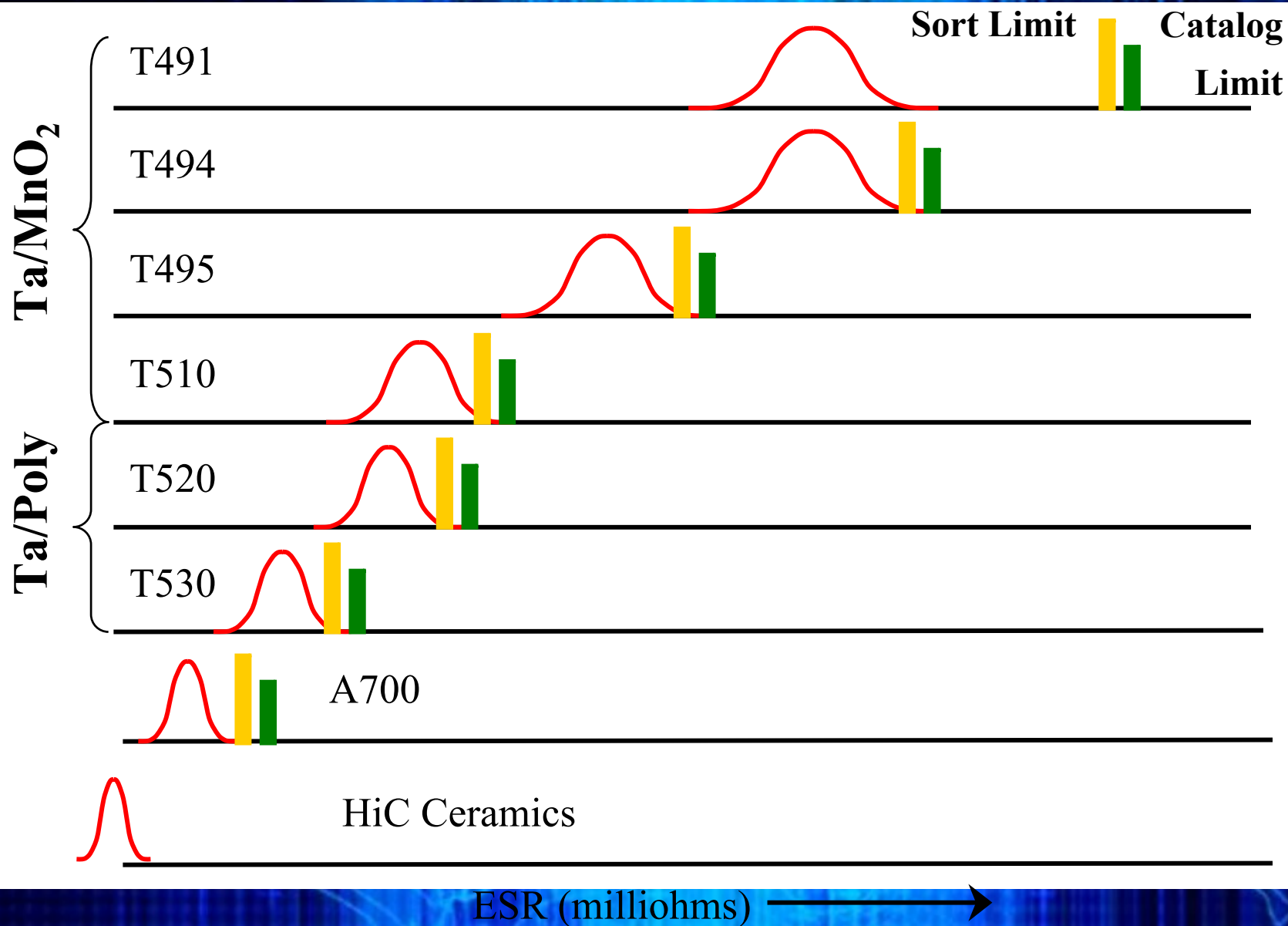


# Power-on Failure Test (SSST)

	MnO <sub>2</sub>	Ta-Poly KO V <sub>R</sub> >10	Ta-Poly KO V <sub>R</sub> ≤10
100 PPM FR % V <sub>Rated</sub>	68%	126%	197%
@50% V <sub>Rated</sub> FR(PPM)	9	0	0
@80% V <sub>Rated</sub> FR(PPM)	458	4	1
@90% V <sub>Rated</sub> FR(PPM)	1,700	12	2
@100% V <sub>Rated</sub> FR(PPM)	6,310	35	8

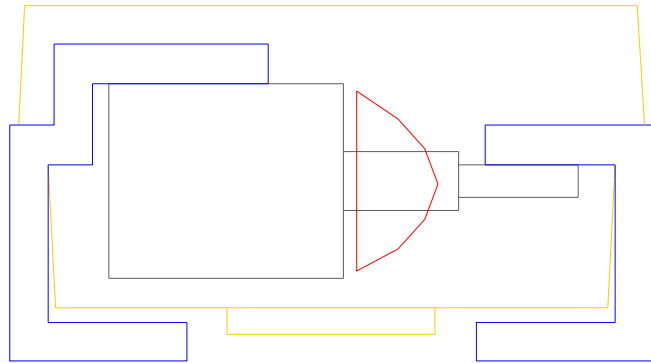


# ESR Distribution

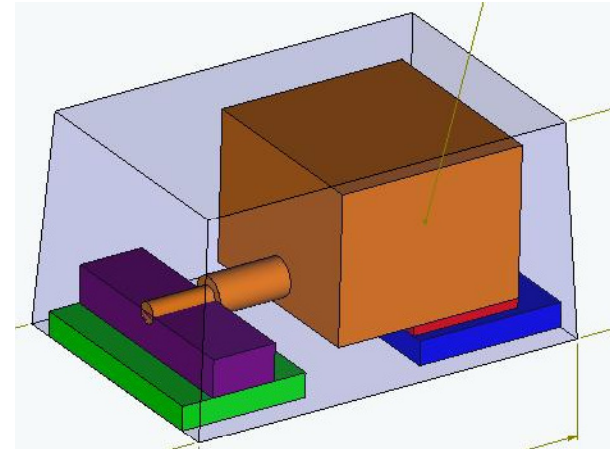


# Small Case Improvements

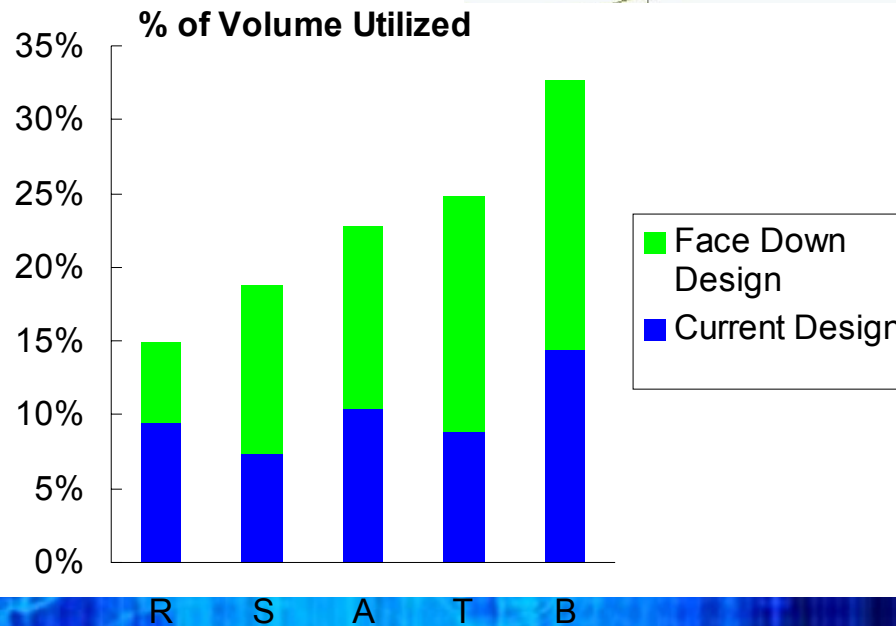
## Standard Construction



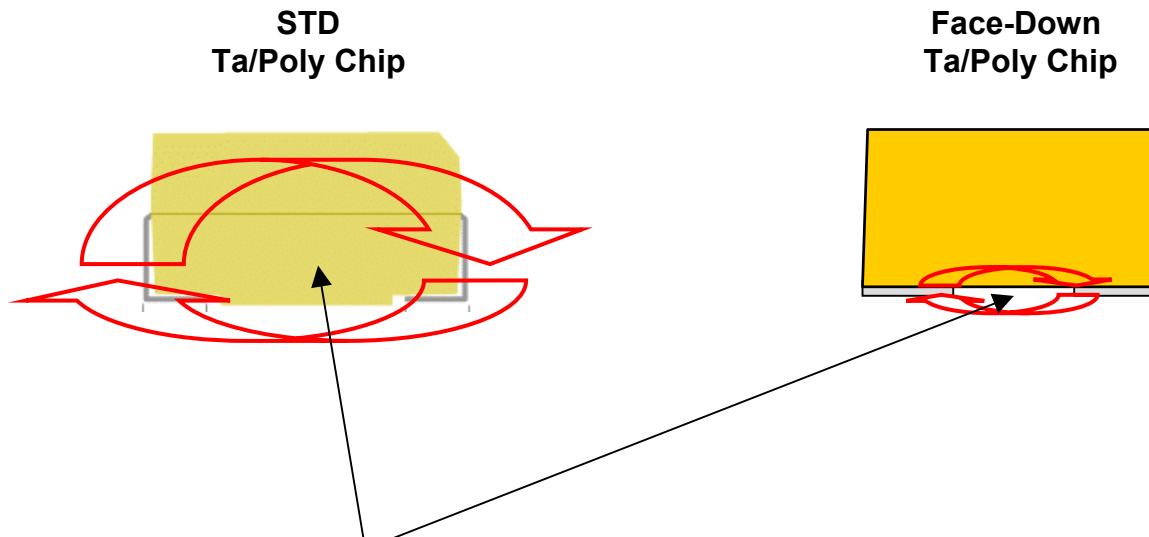
## Facedown Termination



**Increased  
Volumetric  
Efficiency**



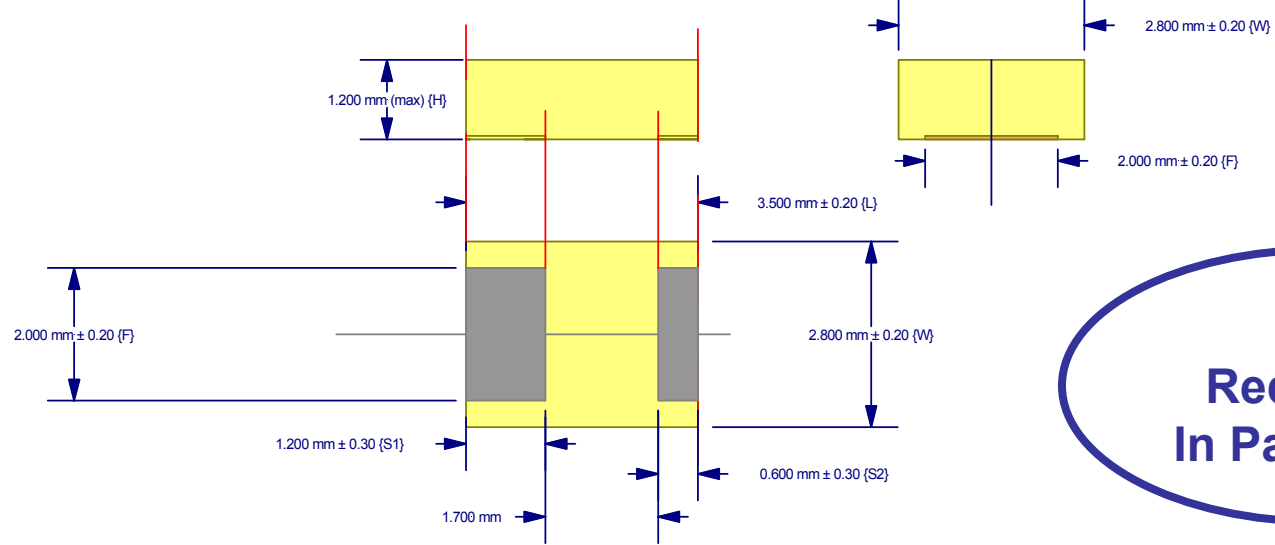
# Reduced ESL Loop Areas



Reduction in “loop area” is proportional to a reduction in ESL.

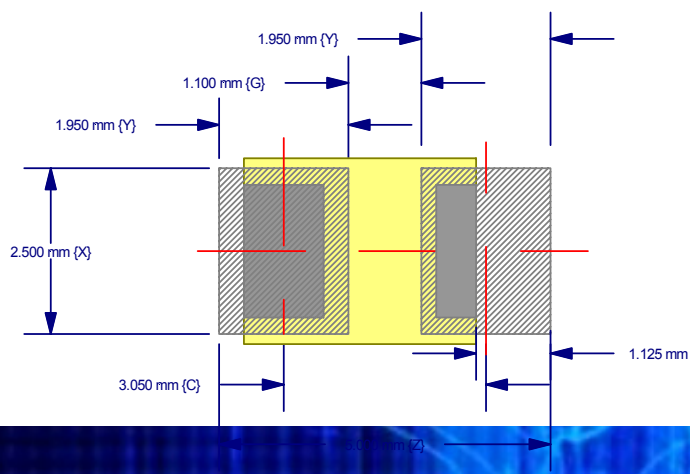
# Solder Pad Layouts: T-Case

## T3528-12 Face-Down

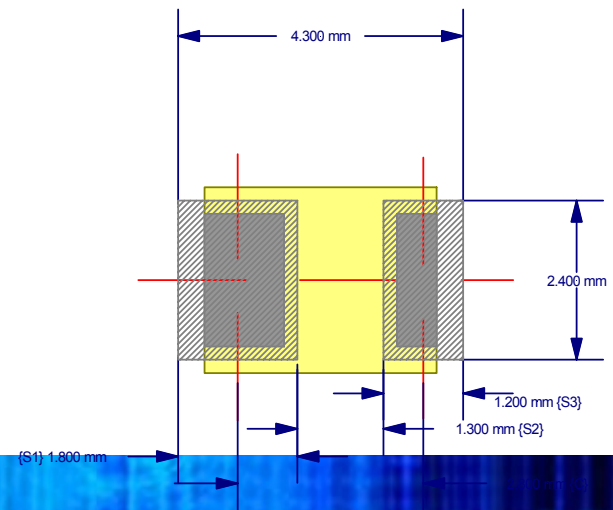


**20%  
Reduction  
In Pad Space**

### Using Standard 3528 Solder Pads



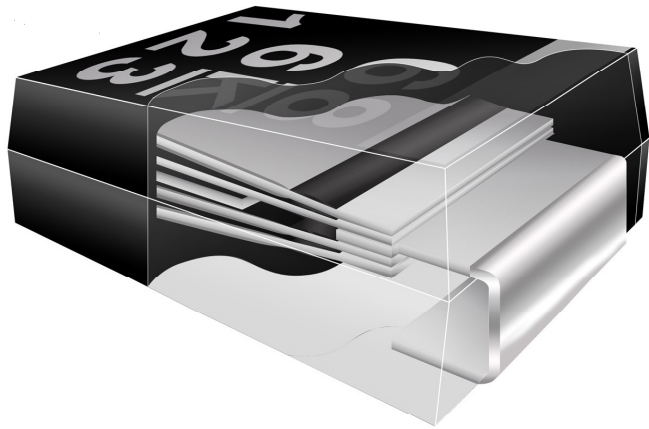
### Using 3528/FD Solder Pads



# Product offering (July 05)

Style	Cases	Capacitance	Voltage
T520	A (3216-18)	686 – 226	2.5 – 6
	B (3528-21)	227 – 336	2.5 – 10
	C (6032-28)	337 – 157	2.5 – 6
	D (7343-31)	687 – 156	2.5 – 25
	V (7343-20)	477 – 226	2 – 25
	W (7343-15)	157 – 336	6 – 16
	X (7343-43)	108 – 337	2.5 – 10
	Y (7343-40)	108 – 337	2.5 – 10

# Aluminum Polymer



- Solid state polymer cathode system – similar to Ta-Poly
- Low ESR, small capacitance roll-off
- Aluminum Anode
- Surface mount